JOSEPHSON EFFECT IN SN-N-NS WEAK LINKS

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For a long time SNS type variable-thickness bridges (VTB) have been considered as promising structures for applications of Josephson effect. The first theoretical estimates  $^{1-3}$  have shown high  $I_{\rm c}R_{\rm N}$  product ( $I_{\rm C}-$  is the critical current,  $R_{\rm N}-$  is the normal state resistance) and much less capacitance compared with the tunnel junctions. There were two main problems in realization of VTB with suitable characteristics. The first was the requirement to provide a presize submicrometer gap between superconducting electrodes. The second was the difficulty with an optimum choice of S- and N-materials for a junction because of the lack of theoretical calculations related with this question. These were the main reasons for great development of tunnel junction technology.  $^{\circ}$ 

Now it is possible to fabricate VTBs due to the technology achievements in reproducing nanometer elements. Experimental VTBs with O.I. weak link lengths have been described in recent works 4.5. However, only the capabilities of submicrometer technology were demonstrated in these works and there was no discussion of electrodes and span materials, choice.

The aim of the report is to ground theoretically the materials' choice for SNS type VTBs which provide a relatively high  $\rm I_{\rm C}R_{\rm N}$  product (  $\rm > I$  mV) and to verify a theory by experimental investigation of Nb-Al-Nb VTB.

# SN-N-NS microbridge model

Fig.I shows a scheme of bridge geometry where SN-sandwich is used as an electrode. This fact leads to nonuniform superconducting gap suppression in S-layer by proximity effect with N-layer. By its turn the critical current  $I_{\rm C}$  decreases. Influence of the proximity effect  $^6$  depends on the parameter.

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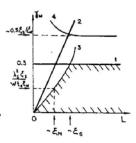
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Fig. 3. The weak link parameters range (dashed) on ( T., 1) plane where one can neglect: I - proximity effect, 2 - superconductivity suppression in electrodes by ourrent, 3 - cross-section superconducting phase difference accumulation, 4 - back influence of proximity effect between span and composit SN electrode. Solid lines separate the regions where the above effects can be neglected, the dashed field is intersection of these regions.



The main parameters of the Josephson juentions are the characteristic voltage  $V_c = I_c R_{\rm H}$ , normal state resistance  $R_{\rm H}$  and capacitance which is very small for VTBs. We shall find the conditions under which  $V_c$  is high and  $R_{\rm H}$  is not very small. Note that the optimum parameter values depend on optimization criteria.

For the first criterion we have chosen a slightness of the proximity effect because it is the main in suppressing  $I_cR_H$ . For example, we shall require  $I_cR_H$  reduction by a factor of two. This criterion is suitable because it results in  $V_c \geq ImV$  that is desirable for the most applications. As is shown it is true under condition (2).

All previous considerations have been carried out under the following assumptions: I) there is no superconductivity suppres-

5 N	Рb	Nb	Nb <sub>3</sub> Sn	NPN
Si* (monocryst) n*= 10 <sup>20</sup> cm <sup>-3</sup>	2.10-3	3-10-3	2 -10 -2	4.10-2
Si* (policryst.) n*=10 <sup>20</sup> cm <sup>-3</sup>	3-10-2	3.10-5	0.2	0.4
n-InAs 8 n°= 3-1018 m-3	5-10-5	4.10-3	3-10-2	7-10-2

Table I. Parameter  $\gamma = (\sigma_N \xi_S)/(\sigma_S \xi_N)$  for widely used S and H materials 1.

 $T_{M} = \frac{\sigma_{N} \dot{\xi}_{S}}{\sigma_{S} \dot{\xi}_{N}} \frac{d_{N}}{\xi_{N}}, \qquad (1)$ 

where  $\sigma_{s,N}$  - are the normal state conductivities,  $\zeta_{s,N}$  - are the coherence lengths of S- and N- materials,  $d_{||}$  - thickness of N-layer  $(d_{||} \ll \xi_N)$ . When  $T_M \ll 1$  a proximity effect is small and critical current is equal to maximum value  $I_0^{-6}$ . For arbitrary



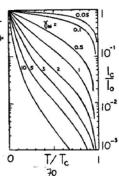
Fig.I. A scheme geometry of SN-N-NS VTB. I-week link length,  $d_N$ - N -layer thickness.  $(d_N \ll \xi_N)$ .

the critical current  $I_c$  have been numerically calculated in "dirty" limit. Pig.2 shows  $I_c(T)$  functions for long  $(L \gg \xi_N)$ , I-weak link length) bridges. In the average temperature range  $T \approx T_c/2$  for  $T_M = I \ I_c/I_o$  is equal to 0.I and 0.0I at  $T \approx T_c$ . Both for short  $(L \leqslant \xi_N)$  and long bridges critical current is greately suppresed in the critical temperature range  $T \approx T_c$ . Calculations have shown that for the most interesting range of the bridge parameters  $L \leqslant 3\xi_N$ ,  $T \approx T_c/2$  a critical current is about two times less as compared to the maximum value  $I_c$  under condition.

$$T_{\rm M} \lesssim 0.3$$
 (2)

## Bridge parameters optimization

Pig.2. Normalized critical current I<sub>c</sub>/I<sub>o</sub> in L ≯ξ<sub>N</sub> limit vs reduced temperature T/T<sub>c</sub> for various I<sub>M</sub> · I<sub>o</sub> = 64π T/(eI<sub>N</sub>)\* Δ<sup>2</sup><sub>∞</sub>· L/ξ<sub>N</sub>· exp(-L/ξ<sub>N</sub>)\* (πT+Δ\*+Z[Δ\*(Δ\*πT)]/2]<sup>2</sup> critical current for I<sub>M</sub> = 0 where Δ\* [(πT)\*+Δ<sup>2</sup><sub>∞</sub>]<sup>N/2</sup>, Δ∞ - equilibrium order parameter in S-layer (K<sub>R</sub>= fi = I).



in the case of bridge over superconducting screen. Here  $\lambda_{\rm S}$  - is the magnetic field penetration depth for S-metal, W - bridge width,  $t_{\rm A}$  - effective distance from the superconducting screen.

We have estimated the widely used materials. Table I shows the parameter  $\gamma=(\sigma_N\xi_s)/(\sigma_s\xi_N)$  for several S and N pairs. Assuming  $N\approx 2/\mu$ ,  $t_e\approx 0.3/\mu$  for the best pair Nb-InAs N0 one obtains a restriction on  $\gamma$ 



Fig. 5. Microphotograph of Nb-Al-Nb microbridge.

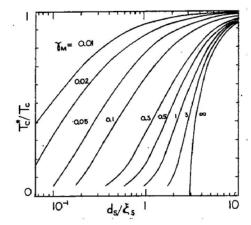
$$\gamma \left\{ \frac{\lambda_s^2 \xi_s}{W t_e \xi_N} \frac{\xi_N}{d_N} \approx 10^{-5} \frac{\xi_N}{d_N} \right\}, \tag{4}$$

which yields

$$d_N \leq (d_N)_{max} \approx 0.3 \xi_N \approx 20 \text{ nm}.$$
 (5)

Such a bridge should have a normal state resistance  $R_N \approx -10\Omega$ . These estimates show that for fabricating VTB with high  $I_{\rm c}R_N$  it is necessary to produce thin (  $\sim 20$  - 40 nm) normal conductivity higholmic layers. The fabrication of such layers by means of evaporation or ion impurity implantation to semiconductor surface is on the verge of possibilities of these methods. Thus, it is desirable to find the new methods for a fabrication such layers, providing small  $\gamma_{\rm m}$ . The outlook materials are monocrystal n-type layers with a high carrier mobility on the semiconductor surface obtained by molecular beam epithaxy. However

sion in electrodes by current, 2) back influence of proximity effect between span and composit SN-electrode is slight, 3) junction is concentrated one. As is was shown  $^7$  these three conditions give rise to additional restrictions on  $\gamma_{\rm M}$ . Fig. 3 shows the range of the junction parameters on ( $\gamma_{\rm M}$ ,L) plane (dashed) where one can neglect all above processes decreasing  $\Gamma_{\rm C}R_{\rm N}$ . It



Pig.4. Critical temperature  $T^*$  of SN sandwich with thin N-layer  $(d_N \ll \mathcal{L}_N)^C$  as a function S-layer thickness  $d_S$  for various  $T_N$ .  $T_C$  - critical temperature of the bulk S-metal,  $T_{CN}^{-}$  0.

remains to choose optimum weak link length L. Because of exponential  $V_{\mathbf{C}}(L)$  decreasing at  $L \gg \xi_{N}$  it is nesessary to take  $L \leqslant \xi_{N}$ . However, very small L leads to strong restrictions on  $\Upsilon_{M}$  and also to small  $R_{N}$  ( $R_{N} \leadsto L$ ). The optimum length is  $L \approx \xi_{N}$  from the point of view of these contradictory requirements. Parameter is to be very small

$$\gamma_{\rm M} \leq \frac{\lambda_{\rm S}^2 \xi_{\rm S}}{w t_{\rm e} \xi_{\rm N}}$$
 (3)

worse a superconductivity of Nb film s and Al film structure. Fir.5 shows a microphotograph of Nb-Al-Nb VTB with  $d_N \simeq 0.05 \, \mu$ ,  $d_S \simeq 0.2 \, \mu$ , W  $\approx 1 \, \mu$ , L  $\approx 0.25 \, \mu$ . Nevertheless, Nb-Al-Nb bridge is not optimum, it allows examination of our theory.

## DC properties

Our junctions had a normal state resistance  $R_N$  in the range 0.I ÷ I  $\Omega$ . Typical I-V curve is shown in Fig.6a.  $I_{\rm c}R_{\rm N}$  product is about 50  $^{\rm LV}$  at T = 5.5 K. Such a low  $I_{\rm c}R_{\rm N}$  was caused by strong proximity effect (  $\sigma_{\rm S} = 0.1\sigma_{\rm N}$ ). It means that  $\gamma_{\rm M}$  is relatively great in our case. We can estimate  $\gamma_{\rm M}$  by fitting  $V_{\rm c}(T)$  function (Fig.6b) which yields  $\gamma_{\rm M} \approx 1$ . Believing L- $\zeta_{\rm N}$  and  $\Delta_{\rm o}/e \approx I$  mV for Nb one can obtain the coherence length for Al  $\zeta_{\rm N} \approx 0.1 \, {\rm e}^{\rm N}$  which is in a good agreement with  $\zeta_{\rm N} \approx (\zeta_{\rm o} \ {\rm d_H})^{1/2} \approx 0.3 \, {\rm e}^{\rm L}$ , where  $\zeta_{\rm o} = 1.6 \, {\rm e}^{\rm L}$  is the theoretical coherence length value for a clean bulk aluminium.

#### Conclusion

The variable thickness bridges are the promising structures for applications of the Josephson effect. For production of the optimum VTB it is necessary to choose 5 and N materials providing small  $\gamma_M$ . Degenerated narrow gap semiconductors are the suitable materials for a bridge span. Hevertheless, our theory does not describe the peculiarities of the carrier transport in semiconductors; it correctly reflects the processes which affects the weak link properties.

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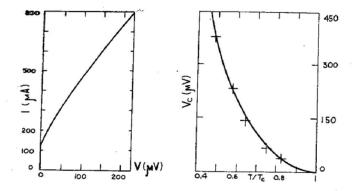


Fig. 6. (a) I-V curve of Hb-Al-Mb VTB with L = 0.25  $\mu$ , R<sub>1</sub> = 0.4  $\Omega$  at T=5.5 K, (b) V<sub>c</sub>(T) - function for the same bridge; solid line - theoretical calculation for L  $\xi \, \xi_{\rm N}$  and  $\gamma_{\rm M} = 1.5$ .

one should have a direct method for measuring  $\gamma_M$  without one of the parameters constructed. One of such methods is critical temperature measurement for SN-sandwich.

It is known that critical temperature  $T_c^*$  of SN-sandwich depends on S-layer thickness  $d_{\rm S}$  because of the preximity effect. For  $d_{\rm S} \to 0$  limit  $T_c^*$  decreases to zero and for  $d_{\rm S} \to \infty$  .  $T_c^*$  aspire to that of bulk superconductor. Fig.4 shows that  $T_c^*(d_{\rm S})$  functions calculated  $^9$  for orbitrary  $T_{\rm M}$  . It is possible to estimate  $T_{\rm M}$  for a certain S-N pair by comparison the experimental and theoretical data. For the purpose  $\xi_{\rm S}$  can be easily obtained from measurements of critical magnetic field Hc2 of S metal near  $T_c$ .

#### Experiment

We have fabricated Nb-Al-Nb VTBs. Aluminium films with the thickness 50-60nm were deposited on Si-substrate with the temperature 200-230°C. It was used a lift off technique for Al strip sampling. Nb films were deposited at high vacuum  $10^{-9}$ — $10^{-10}$ Torr with the thickness 200 nm,  $T_{\rm c}=90$ K, and  $R_{300}/R_{10}=6$ . The preferable sample technique for Nb is plasma-chemical etching (FC3) because the contrary ion or ion-chemical etching PC3 doesn't make

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